

## **C1812X560JHGACTU**

**Specifications** 

Insulation Resistance

Aliases (C1812X560JHGAC7800) SMD Comm COG HV Flex, Ceramic, 56 pF, 5%, 3,000 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 1812, 2.3 mm



General Information	
Series	SMD Comm COG HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra- Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1812
L	4.5mm +/-0.4mm
W	3.2mm +/-0.3mm
Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.7mm +/-0.35mm

Capacitance	56 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	5%
Voltage DC	3000 VDC
Dielectric Withstanding Voltage	3,600 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour

100 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

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